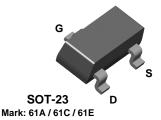


PN4117 **PN4118 PN4119** 

# **MMBF4117 MMBF4118 MMBF4119**





NOTE: Source & Drain are interchangeable

# **N-Channel Switch**

This device is designed for low current DC and audio applications. These devices provide excellent performance as input stages for sub-picoamp instrumentation or any high impedance signal sources. Sourced from Process 53.

#### **Absolute Maximum Ratings\*** TA = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
$V_{DG}$	Drain-Gate Voltage	40	V
V <sub>GS</sub>	Gate-Source Voltage	- 40	V
I <sub>GF</sub>	Forward Gate Current	50	mA
T <sub>J</sub> ,T <sub>stg</sub>	Operating and Storage Junction Temperature Range	-55 to +150	°C

<sup>\*</sup>These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

1) These ratings are based on a maximum junction temperature of 150 degrees C.
2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

#### **Thermal Characteristics** TA = 25°C unless otherwise noted

Symbol	Characteristic	Max		Units
		PN4117-4119	*MMBF4117-4119	
$P_D$	Total Device Dissipation Derate above 25°C	350 2.8	225 1.8	mW mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	125		°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction to Ambient	357	556	°C/W

<sup>\*</sup>Device mounted on FR-4 PCB 1.6" X 1.6" X 0.06."

# **N-Channel Switch**

(continued)

μmhos

μmhos

μmhos pF

рF

Symbol	Parameter	Test Conditions	Min	Max	Units
OFF CHA	RACTERISTICS				
V <sub>(BR)GSS</sub>	Gate-Source Breakdown Voltage	I <sub>G</sub> = - 1.0 μA, V <sub>DS</sub> = 0	- 40		V
I <sub>GSS</sub>	Gate Reverse Current	V <sub>GS</sub> = - 20 V, V <sub>DS</sub> = 0 V <sub>GS</sub> = - 20 V, V <sub>DS</sub> = 0, T <sub>A</sub> = 150°C		- 10 - 25	pA nA
$V_{GS(off)}$	Gate-Source Cutoff Voltage	V <sub>DS</sub> = - 10 V, I <sub>D</sub> = 1.0 nA 4117 4118 4119	- 0.6 - 1.0 - 2.0	- 1.8 - 3.0 - 6.0	V V
	RACTERISTICS		00		1 .
	ZACTERISTICS  Zero-Gate Voltage Drain Current*	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 4117 4118 4119	30 80 200	90 240 600	μΑ μΑ μΑ
I <sub>DSS</sub>		4118	80	240	
I <sub>DSS</sub>	Zero-Gate Voltage Drain Current*	4118 4119	80	240	μA

 $V_{DS} = 10 \text{ V}, V_{GS} = 0, f = 30 \text{ MHz}$ 

 $V_{DS} = 10 \text{ V}, V_{GS} = 0, f = 1.0 \text{ kHz}$ 

 $V_{DS} = 10 \text{ V}, V_{GS} = 0, f = 1.0 \text{ MHz},$ 

4117

4118

4119

60

70

90

3.0

1.5

R<sub>e(yfs)</sub>

 $C_{\text{iss}}$ 

 $C_{\text{rss}}$ 

Common-Source Forwad

Reverse Transfer Capacitance

Transconductance

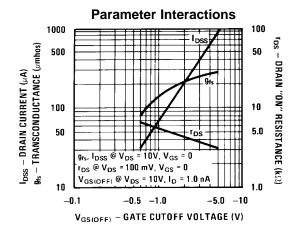
Input Capacitance

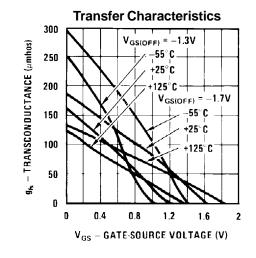
<sup>\*</sup>Pulse Test: Pulse Width  $\leq\!300\,\mu\text{s},\,\text{Duty Cycle}\,\!\leq\!1.0\%$ 

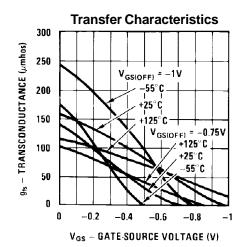
# **N-Channel Switch**

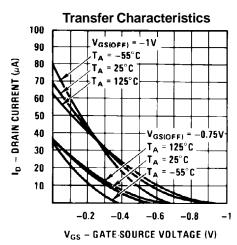
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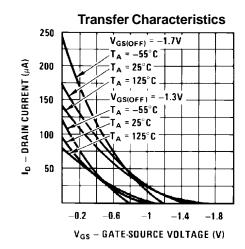
# **Typical Characteristics**

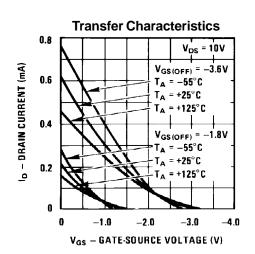








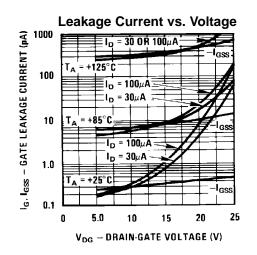


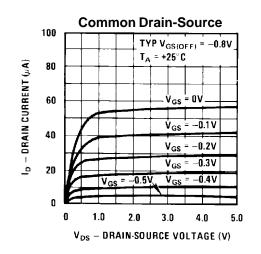


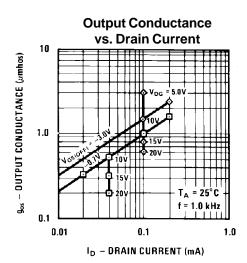
# **N-Channel Switch**

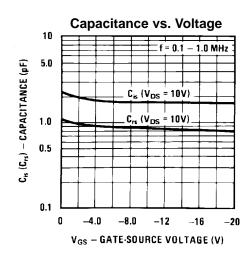
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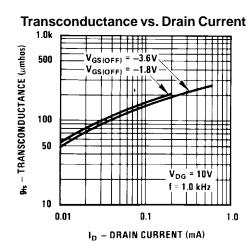
# Typical Characteristics (continued)

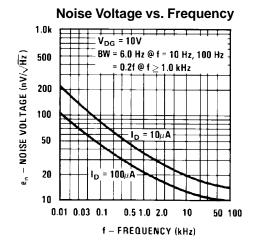












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## PRODUCT STATUS DEFINITIONS

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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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